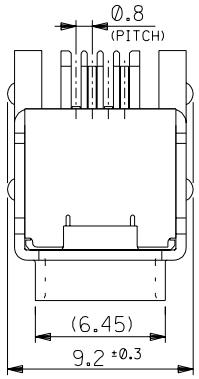
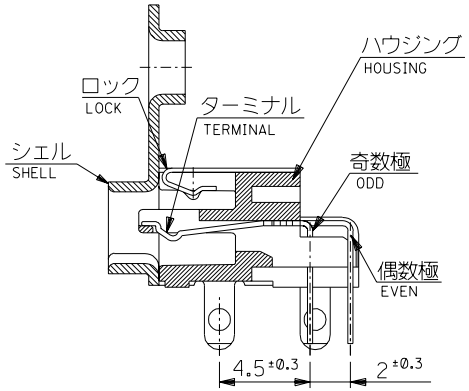
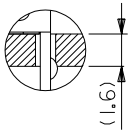
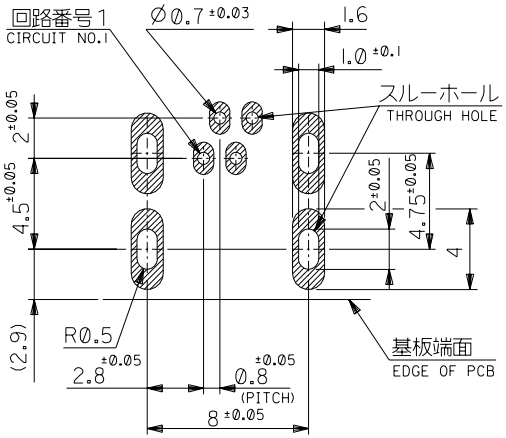




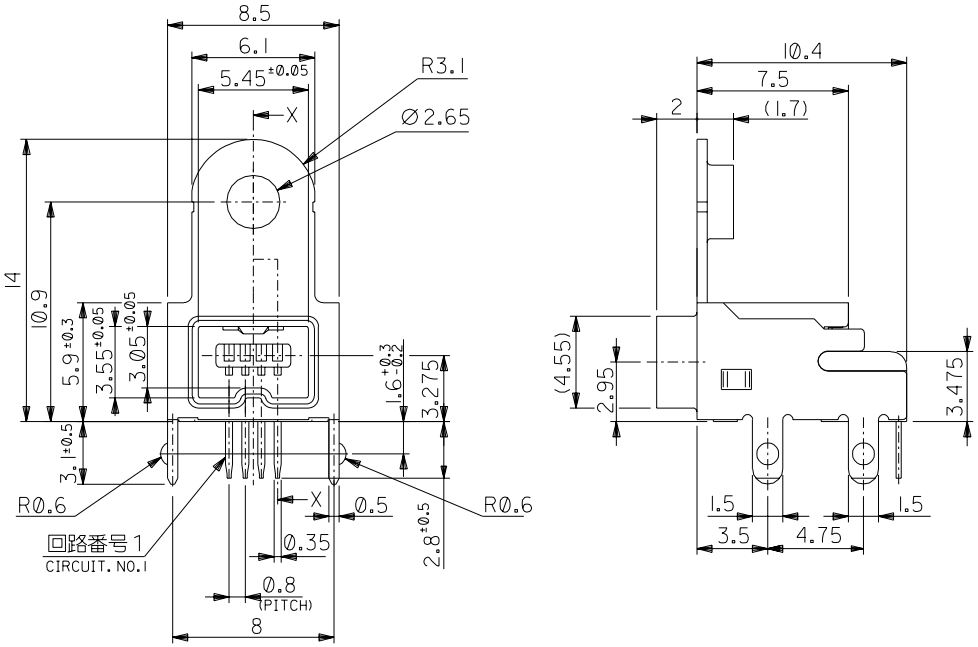
SECT.X-X



基板装着参考図（シェル）
FIGURE OF MOUNTING (SHELL)



推奨基板寸法（実装面側）(t = 1.6)
REFERENCE USE ONLY PCB PATTERM LAYOUT



注記
NOTES

1. 材質 MATERIAL
   - ハウジング：ＰＰＳ、ＵＬ９４Ｖ－０
     HOUSING : PPS , UL94V-0
   - ターミナル：リン青銅　t=0.25
     TERMINAL : PHOSPHOR BRONZE
     - メッキ PLATING
       - 接点部：金メッキ　０．７６マイクロメートル以上
         CONTACT AREA : GOLD 0.76 MICROMETER MIN.
       - 半田付け部：錫メッキ　１．０マイクロメートル以上
         SOLDER TAIL AREA : TIN 1.0 MICROMETER MIN.
       - 下地メッキ：ニッケルメッキ　２．０マイクロメートル以上
         UNDER PLATING : NICKEL 2.0 MICROMETER MIN.
   - シェル：鋼　t=0.5
     SHELL : STEEL
     - メッキ PLATING
       - 半田付け部：錫メッキ　１．０マイクロメートル以上
         SOLDER TAIL AREA : TIN 1.0 MICROMETER MIN.
       - 下地メッキ　：　ニッケルメッキ　１．０マイクロメートル以上
         UNDER PLATING : NICKEL 1.0 MICROMETER MIN.
   - ロック：リン青銅 t=0.2
     LOCK : PHOSPHOR BRONZE
     - メッキ PLATING
       - 錫メッキ　１．０マイクロメートル以上
         TIN-PLATING : 1.0 MICROMETER MIN.
2. 本製品は５４８１８－＊＊１１の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 54818-**11.

54818-0419	4
MATERIAL NO.	CKT.NO.

DO NOT SCALE DRAWING

EC NO.	DRWN:	CH'K:	APPR:	DESCRIPTION	REV
				RELEASED	
J2004-3434	Y.WADA	M.SASAO	M.SASAO	'04/03/30	0

MATERIAL 材料: SEE NOTE
FINISH 仕上げ: SEE NOTE
WIRE RANGE 適用電線範囲: —//—
INS. RANGE 被覆外径: —//—

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差

10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

SCALE 4:1 | DESIGN UNITS ☒mm ☐INCH | THIRD ANGLE PROJECTION

DRAWN BY & DATE: Y.WADA '04/03/30
CHECKED BY & DATE: M.SASAO '04/03/30
APPROVED BY & DATE: M.SASAO '04/03/30

MODEL NO. 54818-**19 | DIMENSIONS: ☐mm/INCH ☐INCH/mm ☒mm ONLY | SHT | REV | REVISE ON CAD ONLY

TITLE: 0.8mm PITCH I/O CONN. SOCKET FLANGE TYPE (HOLE) -LEAD FREE-

MOLEX INCORPORATED

CAD FILENAME: SD-54818-004.S01
MATERIAL NO.: 54818-**19
DRAWING NO.: SD-54818-004
SHEET NO.: 1 OF 1

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SIZE B

EN-02J(097) MXJ-54